



表面安装桥式整流二极管

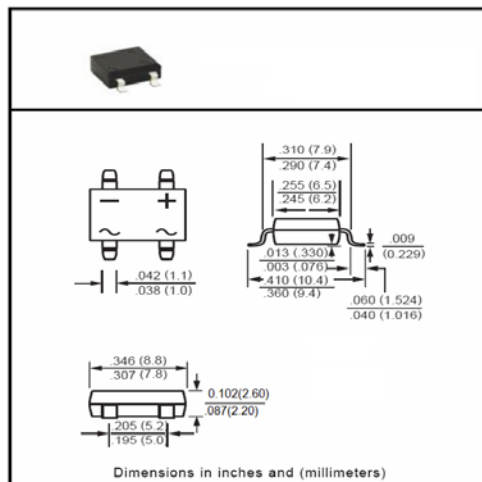
反向电压 50 --- 1000 V

正向电流 1.0A

Surface Mount Bridge Rectifiers

Reverse Voltage 50 to 1000 V

Forward Current 1.0 A



特征 Features

- 玻璃钝化芯片 Glass passivated chip junction
- 较强的正向浪涌承受能力 High forward surge capability
- 高温焊接保证 260°C/10秒 High temperature soldering guaranteed: 260/10seconds at terminals
- 引线 and 管体皆符合RoHS标准。 Lead and body according with RoHS standard

机械数据 Mechanical Data

- 封装: 塑料封装 Case: Molded plastic body
- 端子: 焊料被镀 Terminals: Solder plated
- 极性: 标记模压或印于本体 Polarity: Symbols molded or marked on body
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性 $T_A = 25^\circ\text{C}$ 除非另有规定。Maximum Ratings & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

	Symbols	DF005S	DF01S	DF02S	DF04S	DF06S	DF08S	DF10S	Unit
最大反向峰值电压 Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
最大反向有效值电压 Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
最大直流阻断电压 Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
最大正向平均整流电流 Maximum average forward rectified current	$I_{F(AV)}$	1							A
正向峰值浪涌电流 8.3ms 单一正弦半波 Peak forward surge current 8.3 ms single half sine-wave	I_{FSM}	50							A
最大反向峰值电流 @ $T_A = 75^\circ\text{C}$ Maximum peak reverse current full cycle	$I_{R(AV)}$	30							μA
典型热阻 Typical thermal resistance	$R_{\theta JA}$	40							$^\circ\text{C}/\text{W}$
工作结温和存储温度 Operating junction and storage temperature range	T_J, T_{STG}	-50---+150							$^\circ\text{C}$

电特性 $T_A = 25^\circ\text{C}$ 除非另有规定。Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

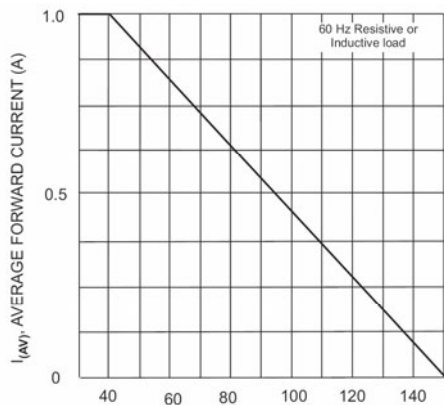
	Symbols	DF005S	DF01S	DF02S	DF04S	DF06S	DF08S	DF10S	Unit
最大正向电压 $I_F = 1.0\text{A}$ Maximum forward voltage	V_F	1.1							V
最大反向漏电流 $T_A = 25^\circ\text{C}$ Maximum reverse current $T_A = 125^\circ\text{C}$	I_R	5.0 500							μA
典型结电容 $V_R = 4.0\text{V}, f = 1\text{MHz}$ Type junction capacitance	C_J	13							pF

Notes: (1) On glass epoxy P.C.B. mounted on 0.05 x 0.05" (1.3 x 1.3 mm) pads

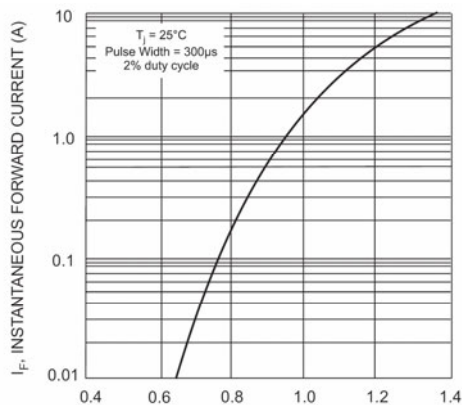
(2) On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20 mm) mounted on 0.05 x 0.05" (1.3 x 1.3 mm) solder pad

特性曲线 ($T_A = 25^\circ\text{C}$ 除非另有规定)

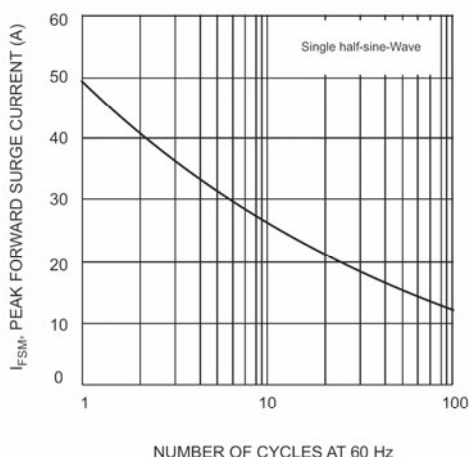
RATINGS AND CHARACTERISTICS CURVES($T_A = 25^\circ\text{C}$ unless otherwise noted)



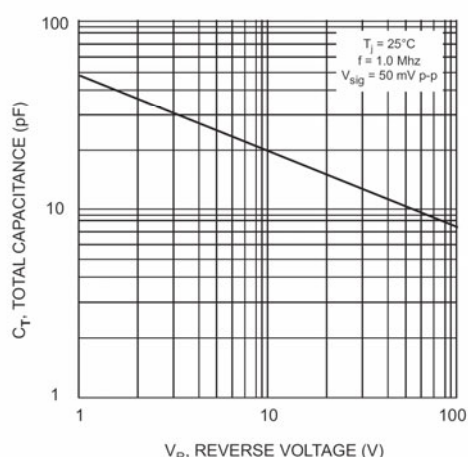
T_A : AMBIENT TEMPERATURE (°C)
Fig. 1 Output Current Derating Curve



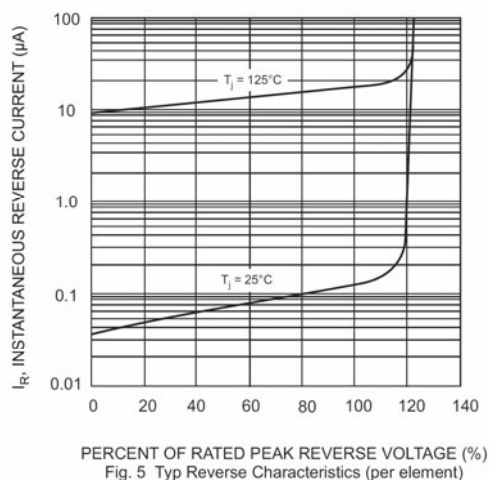
V_F : INSTANTANEOUS FORWARD VOLTAGE (V)
Fig. 2 Typ Forward Characteristics (per element)



NUMBER OF CYCLES AT 60 Hz
Fig. 3 Max Non-Repetitive Peak Forward Surge Current



V_R : REVERSE VOLTAGE (V)
Fig. 4 Typical Total Capacitance (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)
Fig. 5 Typ Reverse Characteristics (per element)